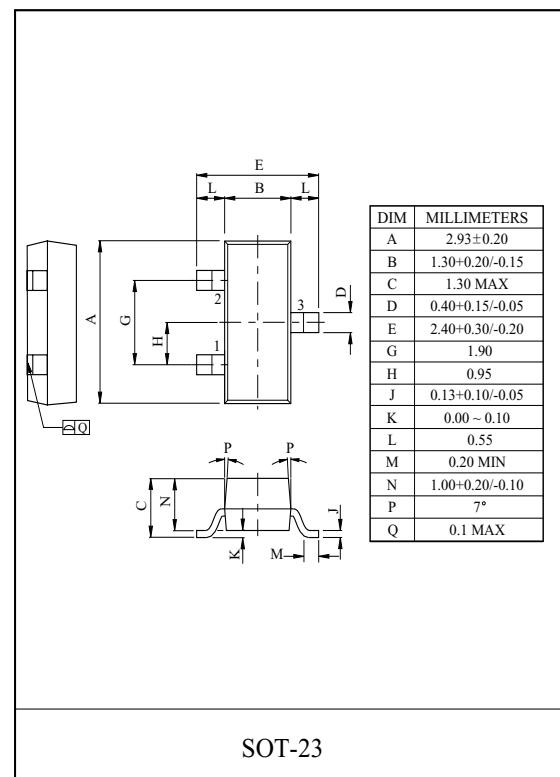


**General Description**

This Trench MOSFET has better characteristics, such as fast switching time, low on resistance, low gate charge and excellent avalanche characteristics. It is mainly suitable for portable equipment.

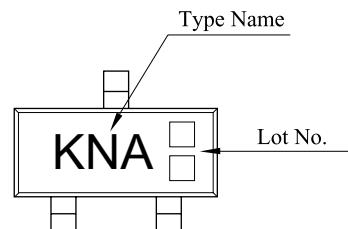
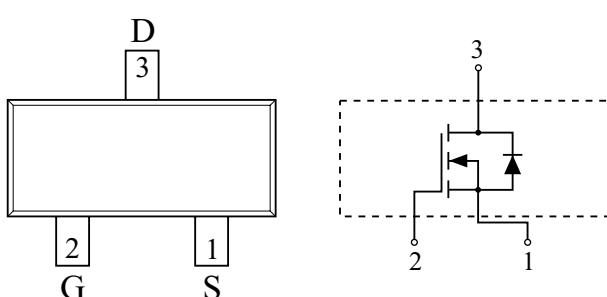
**FEATURES**

- $V_{DSS}=30V$ ,  $I_D=4A$
- Drain-Source ON Resistance  
 $R_{DS(ON)}=47m\Omega$  (Max.) @  $V_{GS}=10V$   
 $R_{DS(ON)}=65m\Omega$  (Max.) @  $V_{GS}=4.5V$
- Super High Dense Cell Design

**MAXIMUM RATING (Ta=25 °C)**

CHARACTERISTIC	SYMBOL	N-Ch	UNIT
Drain-Source Voltage	$V_{DSS}$	30	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current	$I_D$ @ $T_A=25$	4.0	A
	$I_D$ @ $T_A=70$	3.5	
	$I_{DP}$ * Pulsed	20	
Drain-Source-Diode Forward Current	$I_S$	1.04	A
Drain Power Dissipation	$P_D$ @ $T_A=25$	1.25	W
	$P_D$ @ $T_A=70$	0.8	
Maximum Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	
Thermal Resistance, Junction to Ambient	$R_{thJA}$ *	100	/W

Note > \*Surface Mounted on 1 x 1 FR4 Board, t = 5sec

**Marking****PIN CONNECTION (TOP VIEW)**

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## ELECTRICAL CHARACTERISTICS (Ta=25 °C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
<b>Static</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>DS</sub> =250 μA, V <sub>GS</sub> =0V,	30	-	-	V
Drain Cut-off Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =30V	-	-	0.5	μA
		V <sub>GS</sub> =0V, V <sub>DS</sub> =30V, T <sub>j</sub> =55	-	-	10	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>th</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1.0	-	3.0	V
Drain-Source ON Resistance	R <sub>DS(ON)*</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A	-	38	47	m
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =2.8A	-	52	65	
On-State Drain Current	I <sub>D(ON)*</sub>	V <sub>GS</sub> =5V, V <sub>DS</sub> =4.5V	6	-	-	A
Forward Transconductance	g <sub>fs</sub> *	V <sub>DS</sub> =5V, I <sub>D</sub> =2.5A	-	7	-	S
<b>Dynamic</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, f=1MHz, V <sub>GS</sub> =0V	-	305	-	pF
Output Capacitance	C <sub>oss</sub>		-	65	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	29	-	
Total Gate Charge	Q <sub>g</sub> *	V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>D</sub> =2.5A	-	6	9	nC
Gate-Source Charge	Q <sub>gs</sub> *		-	1.6	-	
Gate-Drain Charge	Q <sub>gd</sub> *		-	1.0	-	
Turn-On Delay Time	t <sub>d(on)*</sub>	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V I <sub>D</sub> =1A, R <sub>G</sub> =6	-	7	11	ns
Turn-On Rise Time	t <sub>r</sub> *		-	12	18	
Turn-Off Delay Time	t <sub>d(off)*</sub>		-	14	25	
Turn-Off Fall Time	t <sub>f</sub> *		-	6	10	
<b>Source-Drain Diode Ratings</b>						
Source-Drain Forward Voltage	V <sub>SDF*</sub>	V <sub>GS</sub> =0V, I <sub>DR</sub> =1.25A	-	0.8	1.2	V
NOTE 1> * : Pulse Test : Pulse width <300μs , Duty cycle < 2%						

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Fig1.  $V_{DS}$  -  $I_D$

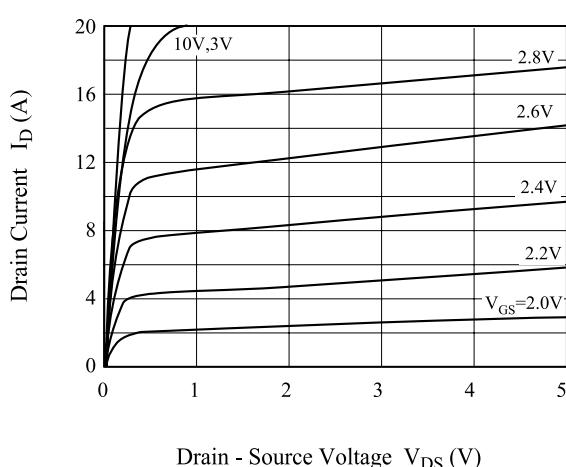


Fig2.  $R_{DS(ON)}$  -  $I_D$

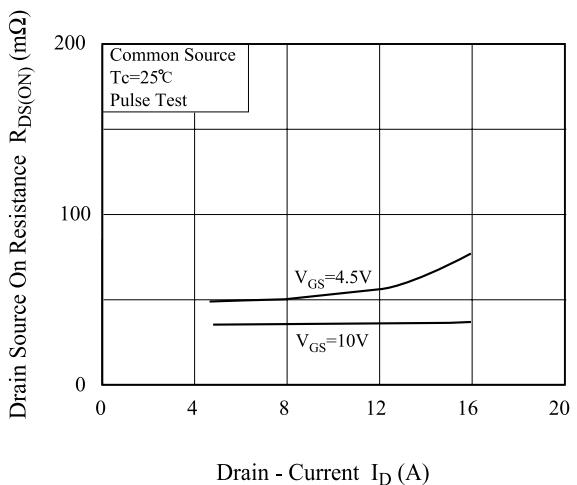


Fig3.  $I_D$  -  $V_{GS}$

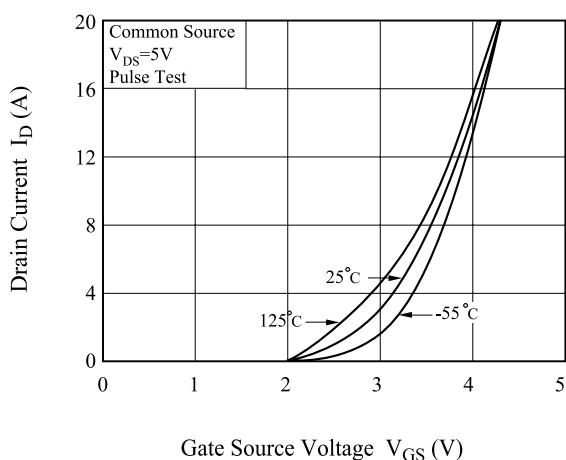


Fig4.  $R_{DS(ON)}$  -  $T_j$

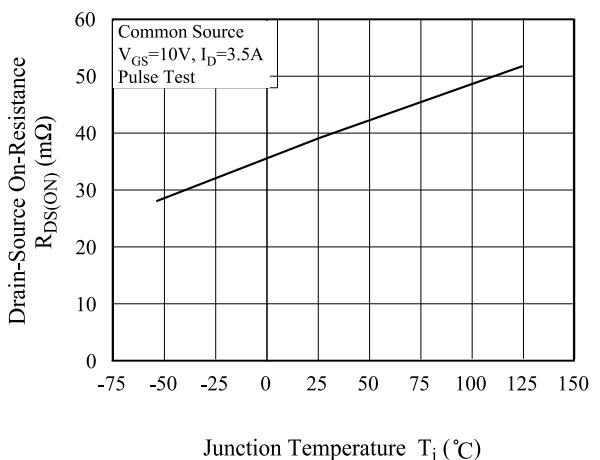


Fig5.  $V_{th}$  -  $T_j$

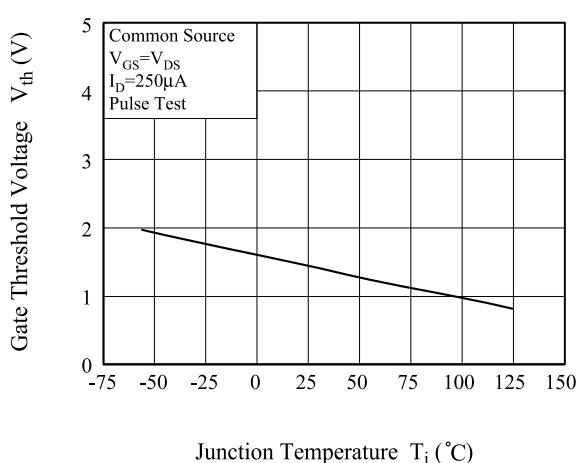
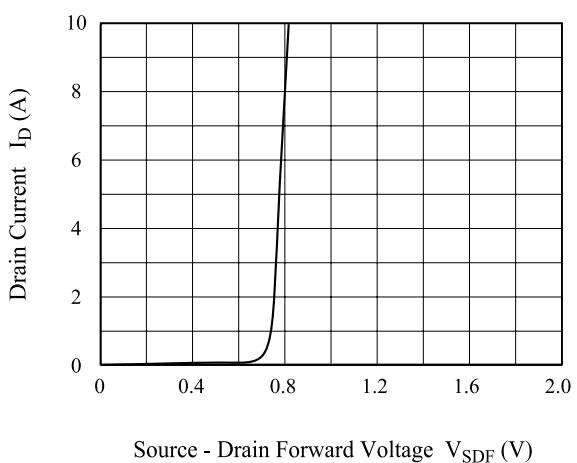


Fig6.  $I_S$  -  $V_{SDF}$



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Fig7. Transient Thermal Response Curve

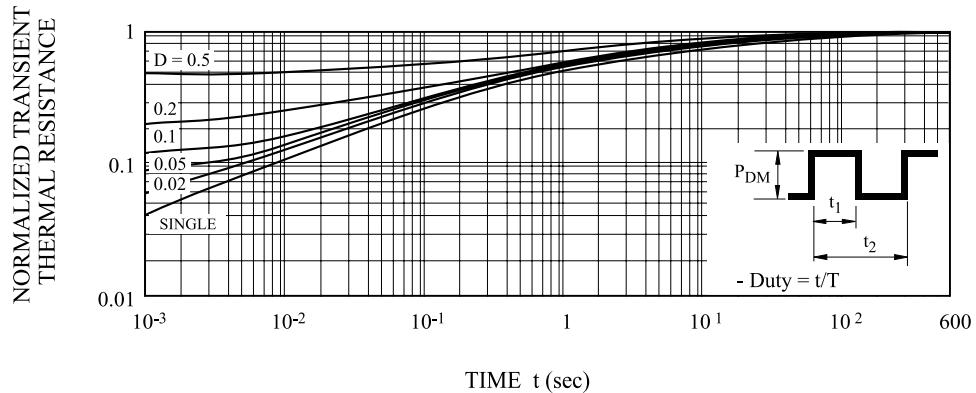
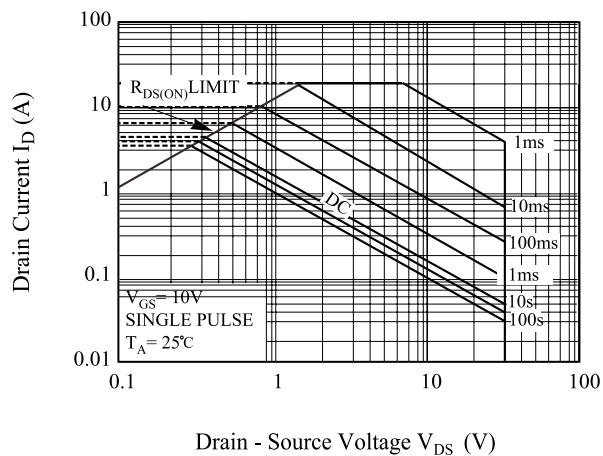


Fig8. Safe Operation Area



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Fig9. Gate Charge Circuit and Wave Form

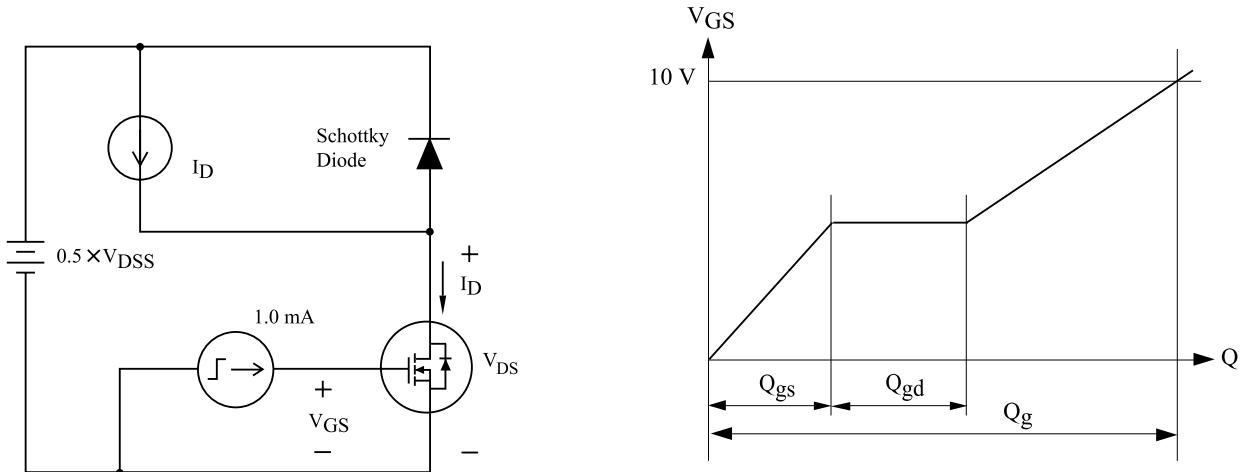


Fig10. Resistive Load Switching

